

IR230DG.HCB SERIES

HIGH POWER RECTIFIER DIODES

- **Junction Size:** Square 230 mils
- **Wafer Size:** 4"
- **V_{RRM} Class:** 600 and 1200 V
- **Passivation Process:** Glassivated MESA
- **Reference IR Packaged Part:** 9AF Series

Major Ratings and Characteristics

Parameters	Units	Test Conditions
V _{FM} Maximum Forward Voltage	1000 mV	T _J = 25°C I _F = 25 A
V _{RRM} Reverse Breakdown Voltage Range	600 and 1200 V	T _J = 25°C I _R = 100 μA (1)

(1) Nitrogen flow on die edge.

Mechanical Characteristics

Nominal Back Metal Composition, Thickness	Cr - Ni - Ag (1 KA - 4 KA - 6 KA)
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Chip Dimensions	230 x 230 mils (see drawing)
Wafer Diameter	100 mm, with std. < 110 > flat
Wafer Thickness	300 μm
Maximum Width of Sawing Line	130 μm
Reject Ink Dot Size	0.25 mm diameter minimum
Ink Dot Location	See drawing
Recommended Storage Environment	Storage in original container, in dessicated nitrogen, with no contamination

IR230DG..HCB Series

Bulletin I0134J 05/99



Ordering Information Table

Device Code

IR	230	D	G	12	H	CB
1	2	3	4	5	6	7

1

- International Rectifier Device

2

- Chip Dimension in Mils

3

- Type of Device: D = Standard Recovery Diode

4

- Passivation Process: G = Glassivated MESA

5

- Voltage code: Code x 100 = V_{RRM}

6

- Metallization: H = Silver (Anode) - Silver (Cathode)

7

- Probed Uncut Die

Available Class

06 = 600V

12 = 1200V

Outline Table

5.8

4.4

2.0 ref.

5.8

1.3 ref.

4.4

0.30 ± 0.01

Ag

Ag

INK DOT WITH LOCATION SITE

All dimensions are in millimeters

Wafer Layout

